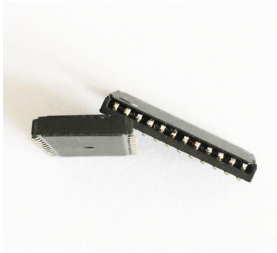


Features:



Notice : This is a RoHS compliant component, All engineering changes must have prior approval by the design center

Plastic: Thermoset plastic material with flammability rating UL 94V-0 or better

Solderability: Conforms to ANSI/J-STD-002, 245°C reflow peak temperature per IPC/EIA J-STD-003A

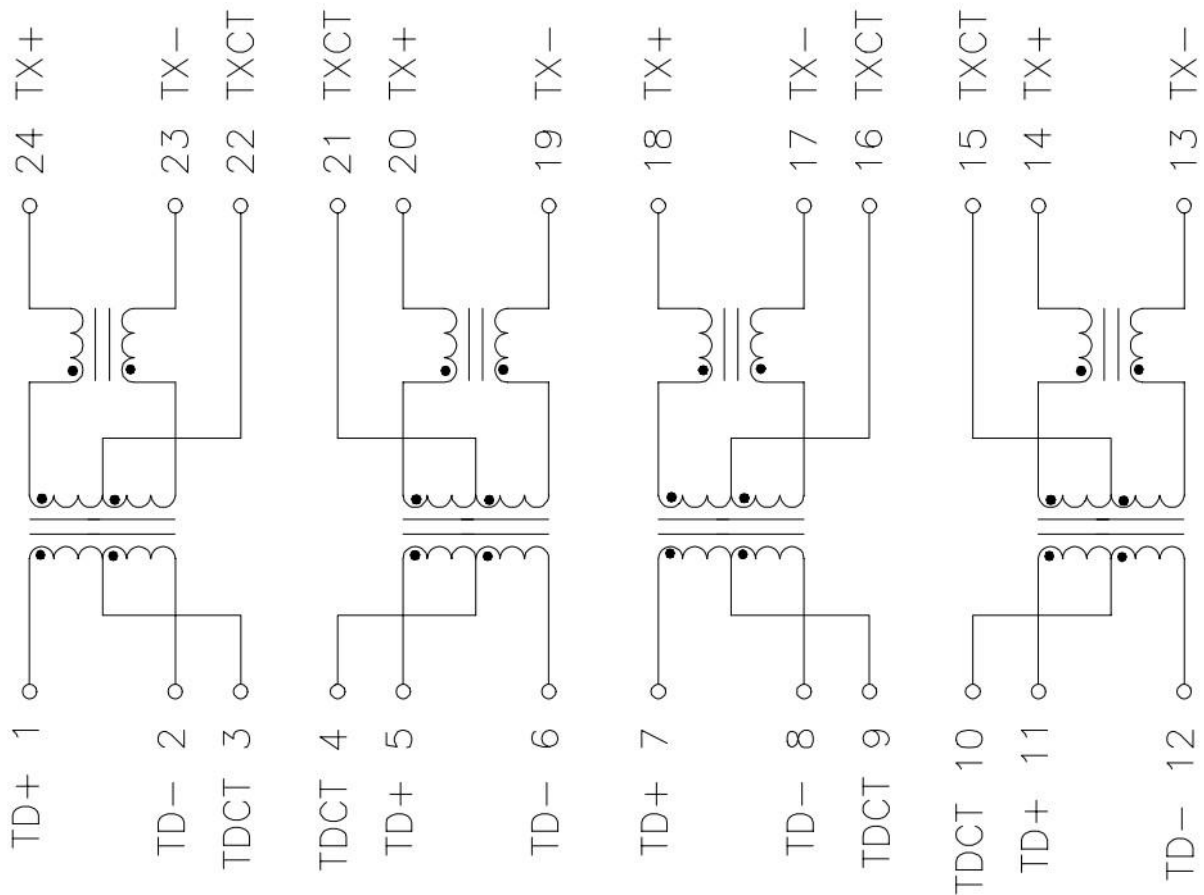
Operating temperature: 0°C~+70°C

Storage temperature: -40°C~+85°C 90%RH

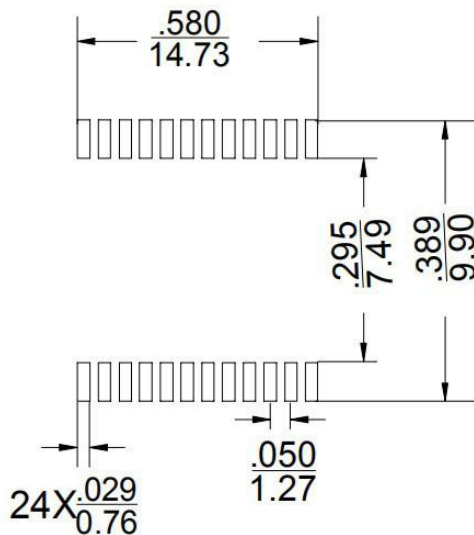
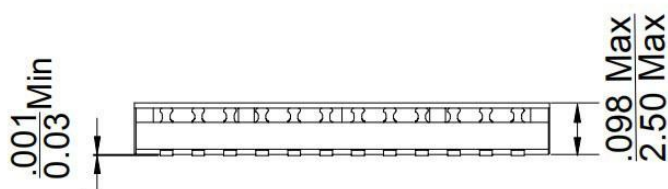
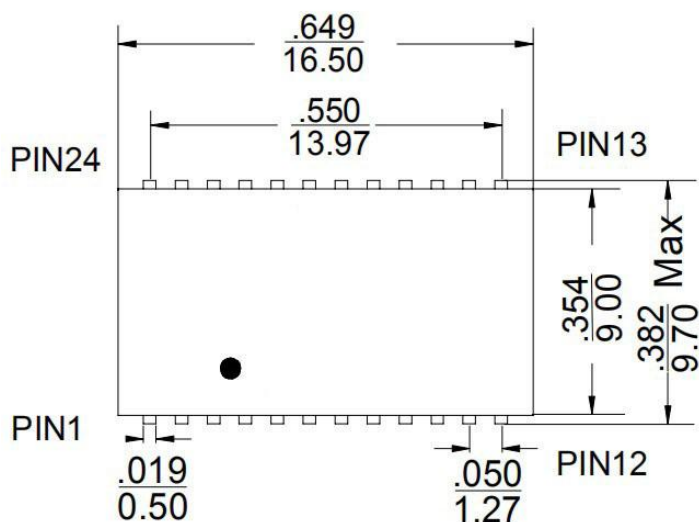
Specifications

Electrical Specification@25° C Operating Temperature 0 to +70° C										
Part NO	Trun Ratio(±2%)		OCL primary@10 0KHz 0.1Vms		Leakage primary@10KH z 0.1Vms		Cww(Pri:Sec)		DCR(Ω)	
	TX	RX							Primary	Secondary
HM82409S	1CT:1CT	1CT:1CT	350uH Min		0.5uH max		35pF Typ		0.9Max	1.2Max
Electrical Specification@25° C Operating Temperature 0 to +70° C										
Part NO	Insertion loss(dB max) 1-100MHz		Return Loss(db min)MHz				DMRR(dB min)MHz		Crosstalk(dB min)MHz	Isolation Voltage(Vrms min)
			1-30	40	50	60-100	1-60	60-100	1-100	
HM82409S	-1.2		-18	-18	-16	-12	-50	-50	-50	1500

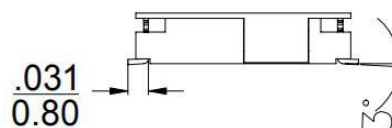
Schematic



Mechanical:



Suggested PCB Pad Layout



	Td	↔	Mx	
CHIP	Td	↔	Mx	MEDIA
SIDE	Td	↔	Mx	SIDE
	Td	↔	Mx	

LEGEND